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TECHNICAL REPORT



**Circuit boards and circuit board assemblies – Design and use –
Part 8: 3D shape data for CAD component library**

INTERNATIONAL
ELECTROTECHNICAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES –
DESIGN AND USE –**

Part 8: 3D shape data for CAD component library

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The language used for the development of this Technical Report is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES – DESIGN AND USE –

Part 8: 3D shape data for CAD component library

1 Scope

This part of IEC 61188 describes the configuration of part shape data of semiconductor devices and electrical components registered in the CAD library.

This document mainly describes the configuration of 2D and 3D parts shape data.

2 Normative references

There are no normative references in this document.